THAT WHICH IS CLAIMED IS:

1. A semiconductor device comprising:

a superlattice comprising a plurality of stacked groups of layers; and

regions for causing transport of charge carriers through said superlattice in a parallel direction relative to the stacked groups of layers;

each group of layers of said superlattice comprising a plurality of stacked base semiconductor monolayers defining a base semiconductor portion and an energy band-modifying layer thereon;

said energy-band modifying layer comprising at least one non-semiconductor monolayer constrained within a crystal lattice of adjacent base semiconductor portions so that said superlattice has a higher charge carrier mobility in the parallel direction than would otherwise be present.

- 2. A semiconductor device according to Claim 1 wherein said superlattice has a common energy band structure therein.
- 3. A semiconductor device according to Claim 1 wherein the charge carriers having the higher mobility comprise at least one of electrons and holes.
- 4. A semiconductor device according to Claim 1 wherein each base semiconductor portion comprises silicon.
- 5. A semiconductor device according to Claim 1 wherein each energy band-modifying layer comprises oxygen.

- 6. A semiconductor device according to Claim 1 wherein each energy band-modifying layer is a single monolayer thick.
- 7. A semiconductor device according to Claim 1 wherein each base semiconductor portion is less than eight monolayers thick.
- 8. A semiconductor device according to Claim 1 wherein each base semiconductor portion is two to six monolayers thick.
- 9. A semiconductor device according to Claim 1 wherein said superlattice further has a substantially direct energy bandgap.
- 10. A semiconductor device according to Claim 1 wherein said superlattice further comprises a base semiconductor cap layer on an uppermost group of layers.
- 11. A semiconductor device according to Claim 1 wherein all of said base semiconductor portions are a same number of monolayers thick.
- 12. A semiconductor device according to Claim 1 wherein at least some of said base semiconductor portions are a different number of monolayers thick.
- 13. A semiconductor device according to Claim 1 wherein all of said base semiconductor portions are a different number of monolayers thick.

- 14. A semiconductor device according to Claim 1 wherein each non-semiconductor monolayer is thermally stable through deposition of a next layer.
- 15. A semiconductor device according to Claim 1 wherein each base semiconductor portion comprises a base semiconductor selected from the group consisting of Group IV semiconductors, Group III-V semiconductors, and Group III-VI semiconductors.
- 16. A semiconductor device according to Claim 1 wherein each energy band-modifying layer comprises a non-semiconductor selected from the group consisting of oxygen, nitrogen, fluorine, and carbon-oxygen.
- 17. A semiconductor device according to Claim 1 further comprising a substrate adjacent said superlattice.
- 18. A semiconductor device according to Claim 1 wherein the higher charge carrier mobility results from a lower conductivity effective mass for the charge carriers in the parallel direction than would otherwise be present.
- 19. A semiconductor device according to Claim 18 wherein the lower conductivity effective mass is less than two-thirds the conductivity effective mass that would otherwise occur.
- 20. A semiconductor device according to Claim 1 wherein said superlattice further comprises at least one type of conductivity dopant therein.

21. A semiconductor device comprising:

a superlattice comprising a plurality of stacked groups of layers; and

regions for causing transport of charge carriers through said superlattice in a parallel direction relative to the stacked groups of layers;

each group of layers of said superlattice comprising a plurality of stacked silicon monolayers defining a silicon portion and an energy band-modifying layer thereon;

said energy-band modifying layer comprising at least one oxygen monolayer constrained within a crystal lattice of adjacent silicon portions so that said superlattice has a higher charge carrier mobility in the parallel direction than would otherwise be present.

- 22. A semiconductor device according to Claim 21 wherein said superlattice has a common energy band structure therein.
- 23. A semiconductor device according to Claim 21 wherein the charge carriers having the higher mobility comprise at least one of electrons and holes.
- 24. A semiconductor device according to Claim 21 wherein each energy band-modifying layer is a single monolayer thick.
- 25. A semiconductor device according to Claim 21 wherein each silicon portion is less than eight monolayers thick.

- 26. A semiconductor device according to Claim 21 wherein each silicon portion is two to six monolayers thick.
- 27. A semiconductor device according to Claim 21 wherein said superlattice further has a substantially direct energy bandgap.
- 28. A semiconductor device according to Claim 21 wherein said superlattice further comprises a silicon cap layer on an uppermost group of layers.
- 29. A semiconductor device according to Claim 21 wherein all of said silicon portions are a same number of atomic layers thick.
- 30. A semiconductor device according to Claim 21 wherein at least some of said silicon portions are a different number of monolayers thick.
- 31. A semiconductor device according to Claim 21 wherein all of said silicon portions are a different number of monolayers thick.
- 32. A semiconductor device according to Claim 21 further comprising a substrate adjacent said superlattice.
- 33. A semiconductor device according to Claim 21 wherein the higher charge carrier mobility results from a lower conductivity effective mass in the parallel direction than would otherwise be present.

- 34. A semiconductor device according to Claim 21 wherein said superlattice further comprises at least one type of conductivity dopant therein.

regions adjacent said superlattice for causing transport of charge carriers through said superlattice in a parallel direction relative to the stacked groups of layers;

each group of layers of said superlattice comprising less than eight stacked base semiconductor monolayers defining a base semiconductor portion and an energy band-modifying layer thereon;

said energy-band modifying layer comprising a single non-semiconductor monolayer constrained within a crystal lattice of adjacent base semiconductor portions so that said superlattice has a higher charge carrier mobility in the parallel direction than would otherwise be present.

- 36. A semiconductor device according to Claim 35 wherein said superlattice has a common energy band structure therein.
- 37. A semiconductor device according to Claim 35 wherein the charge carriers having the higher mobility comprise at least one of electrons and holes.

- 38. A semiconductor device according to Claim 35 wherein said superlattice further has a substantially direct energy bandgap.
- 39. A semiconductor device according to Claim 35 wherein said superlattice further comprises a base semiconductor cap layer on an uppermost group of layers.
- 40. A semiconductor device according to Claim 35 wherein all of said base semiconductor portions are a same number of monolayers thick.
- 41. A semiconductor device according to Claim 35 wherein at least some of said base semiconductor portions are a different number of monolayers thick.
- 42. A semiconductor device according to Claim 35 wherein all of said base semiconductor portions are a different number of monolayers thick.
- 43. A semiconductor device according to Claim 35 further comprising a substrate adjacent said superlattice.
- 44. A semiconductor device according to Claim 35 wherein the higher charge carrier mobility results from a lower conductivity effective mass in the parallel direction than would otherwise be present.
- 45. A semiconductor device according to Claim 35 wherein said superlattice further comprises at least one type of conductivity dopant therein.

46. A semiconductor device comprising:

a superlattice comprising a plurality of stacked groups of layers; and

regions for causing transport of charge carriers through said superlattice in a parallel direction relative to the stacked groups of layers;

each group of layers of said superlattice comprising less than eight stacked silicon monolayers defining a silicon portion and an energy band-modifying layer thereon;

said energy-band modifying layer comprising a single oxygen monolayer constrained within a crystal lattice of adjacent silicon portions.

- 47. A semiconductor device according to Claim 46 wherein said superlattice further comprises a base semiconductor cap layer on an uppermost group of layers.
- 48. A semiconductor device according to Claim 46 wherein all of said base semiconductor portions are a same number of monolayers thick.
- 49. A semiconductor device according to Claim 46 wherein at least some of said base semiconductor portions are a different number of monolayers thick.
- 50. A semiconductor device according to Claim 46 wherein all of said base semiconductor portions are a different number of monolayers thick.
- 51. A semiconductor device according to Claim 46 further comprising a substrate adjacent said superlattice.

- 52. A semiconductor device according to Claim 46 wherein said superlattice further comprises at least one type of conductivity dopant therein.
 - 53. A semiconductor device comprising:

a superlattice comprising a plurality of stacked groups of layers; and

regions for causing transport of charge carriers through said superlattice in a parallel direction relative to the stacked groups of layers;

each group of layers of said superlattice comprising a plurality of stacked base semiconductor monolayers defining a base semiconductor portion and an energy band-modifying layer thereon;

said energy-band modifying layer comprising at least one non-semiconductor monolayer constrained within a crystal lattice of adjacent base semiconductor portions so that said superlattice has a lower conductivity effective mass in the parallel direction than would otherwise be present.

- 54. A semiconductor device according to Claim 53 wherein said superlattice has a common energy band structure therein.
- 55. A semiconductor device according to Claim 53 wherein the charge carriers having the lower conductivity effective mass comprise at least one of electrons and holes.

- 56. A semiconductor device according to Claim 53 wherein each base semiconductor portion comprises silicon.
- 57. A semiconductor device according to Claim 53 wherein each energy band-modifying layer comprises oxygen.
- 58. A semiconductor device according to Claim 53 wherein each energy band-modifying layer is a single monolayer thick.
- 59. A semiconductor device according to Claim 53 wherein each base semiconductor portion is less than eight monolayers thick.
- 60. A semiconductor device according to Claim 53 wherein each base semiconductor portion is two to six monolayers thick.
- 61. A semiconductor device according to Claim 53 wherein said superlattice further has a substantially direct energy bandgap.
- 62. A semiconductor device according to Claim 53 wherein said superlattice further comprises a base semiconductor cap layer on an uppermost group of layers.
- 63. A semiconductor device according to Claim 53 wherein all of said base semiconductor portions are a same number of monolayers thick.

- 64. A semiconductor device according to Claim 53 wherein at least some of said base semiconductor portions are a different number of monolayers thick.
- 65. A semiconductor device according to Claim 53 wherein all of said base semiconductor portions are a different number of monolayers thick.
- 66. A semiconductor device according to Claim 53 wherein each non-semiconductor monolayer is thermally stable through deposition of a next layer.
- 67. A semiconductor device according to Claim 53 wherein each base semiconductor portion comprises a base semiconductor selected from the group consisting of Group IV semiconductors, Group III-V semiconductors, and Group III-VI semiconductors.
- 68. A semiconductor device according to Claim 53 wherein each energy band-modifying layer comprises a non-semiconductor selected from the group consisting of oxygen, nitrogen, fluorine, and carbon-oxygen.
- 69. A semiconductor device according to Claim 53 further comprising a substrate adjacent said superlattice.
- 70. A semiconductor device according to Claim 53 wherein the lower conductivity effective mass is less than two-thirds the conductivity effective mass that would otherwise occur.

71. A semiconductor device according to Claim 53 wherein said superlattice further comprises at least one type of conductivity dopant therein.